



## / Absolute Maximum Ratings(Ta=25 )

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RM}$ $V_{RSM}$ $V_{DC}$	100	V
RMS Reverse Voltage	$V_{RMS}$	70	V
Average forward rectified current	$I_{F(AV)}$	1×10	A
Non Repetitive Peak Surge Current	$I_{FSM}$	200	A
Typical Thermal Resistance <sup>Note 1</sup>	$R_{\theta JA}$	70	/W
	$R_{\theta Jc}$	1.4	/W
Junction and Storage Temperature Range	$T_j$ $T_{stg}$	-55 +150	

## / Electrical Characteristics(Ta=25 )

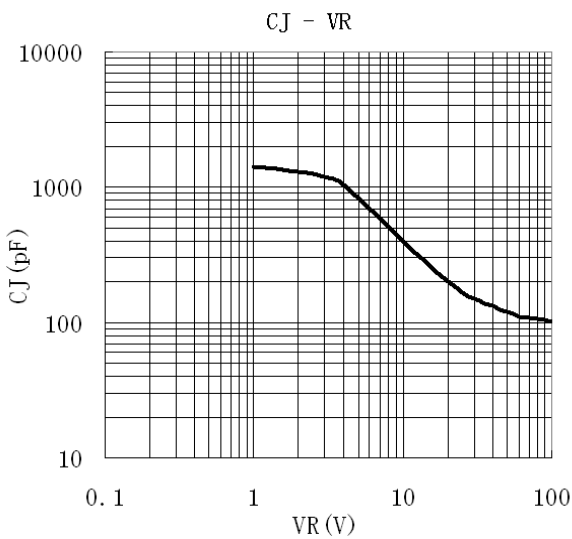
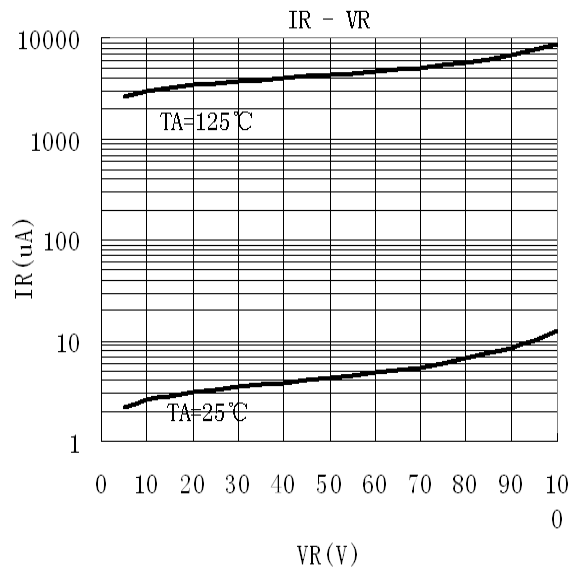
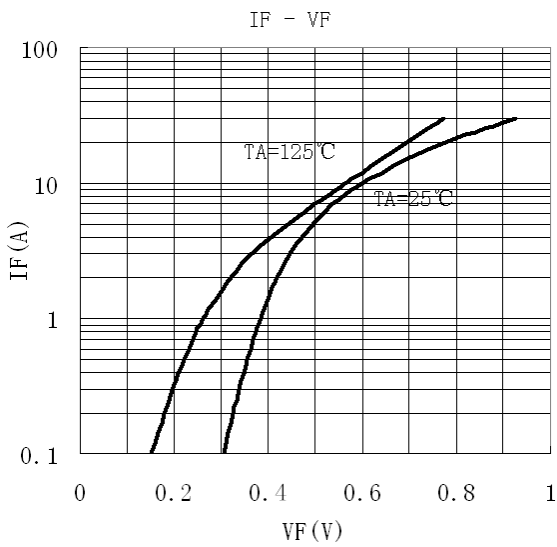
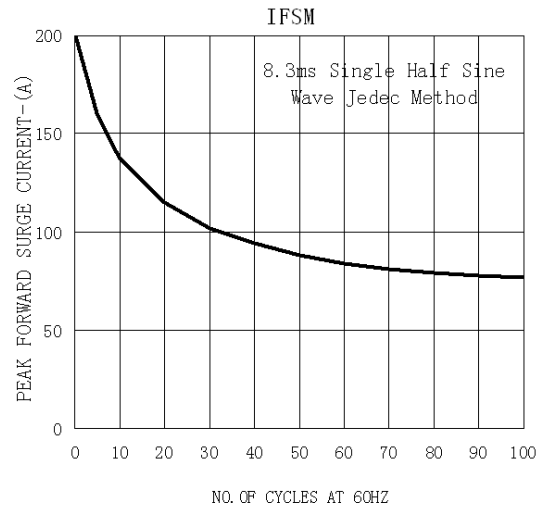
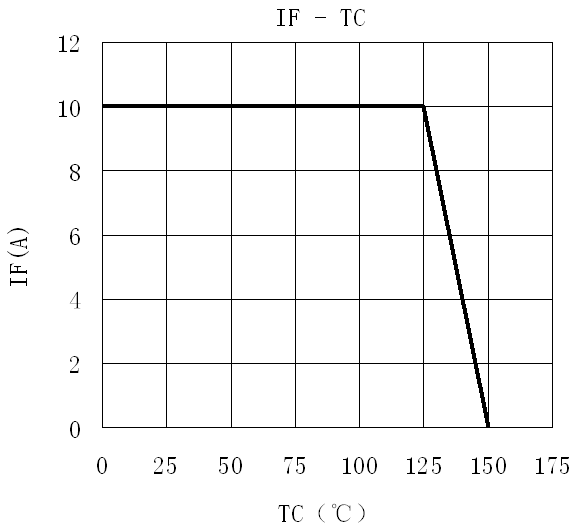
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	$V_{(BR)R}$	$I_R=1mA(Ta=25 )$	100			V
Forward Voltage	$V_F$	$I_F=2A(Ta=25 )$		0.41	0.45	V
		$I_F=10A(Ta=25 )$		0.58	0.65	V
		$I_F=2A(Ta=125 )$		0.31	0.40	V
		$I_F=10A(Ta=125 )$		0.55	0.65	V
Instantaneous Reverse Current	$I_R$ <sup>Note 2</sup>	$V_R=100V(Ta=25 )$			150	$\mu A$
		$V_R=100V(Ta=125 )$			25	mA

Polymide PCB, 2oz. Copper. Cathode pad dimensions 18.8mm x 14.4mm. Anode pad dimensions 5.6mm x 14.4mm.

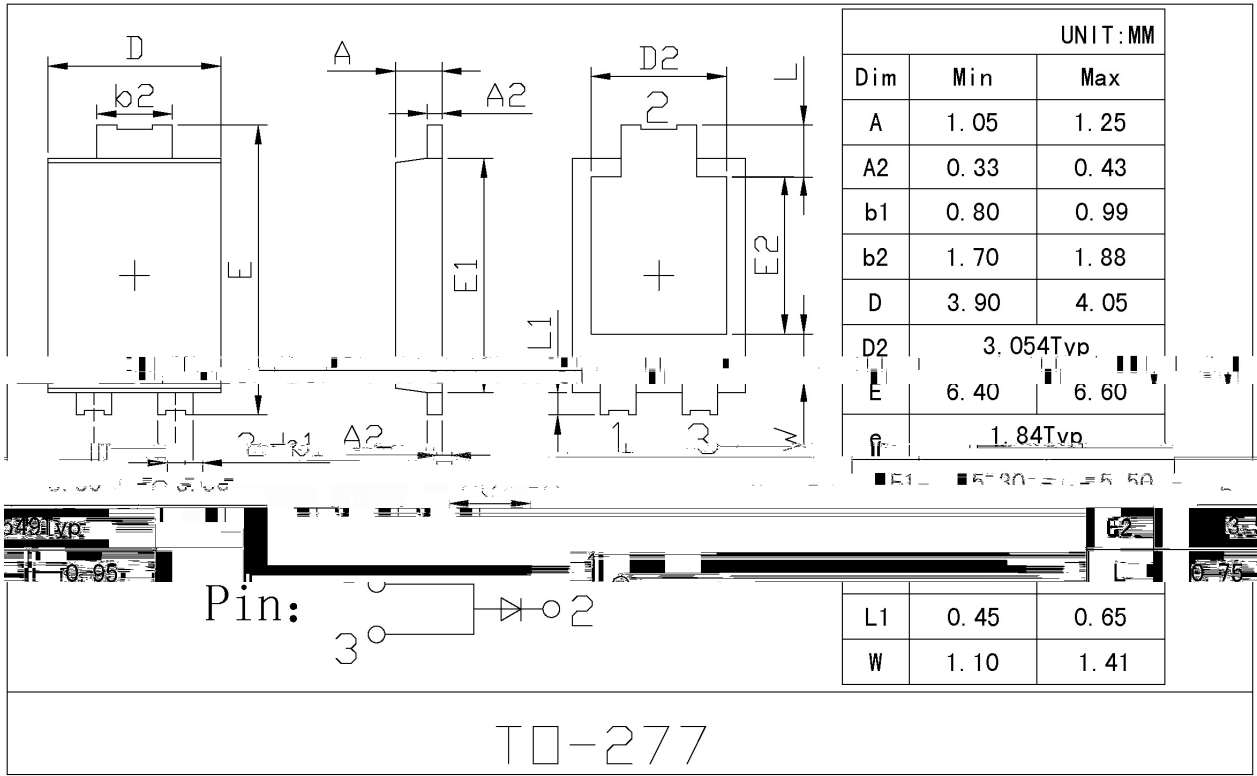
Short duration pulse test used to minimize self-heating effect.

Unless otherwise noted, values for the parameters of a single chip.

**/ Electrical Characteristic Curve**



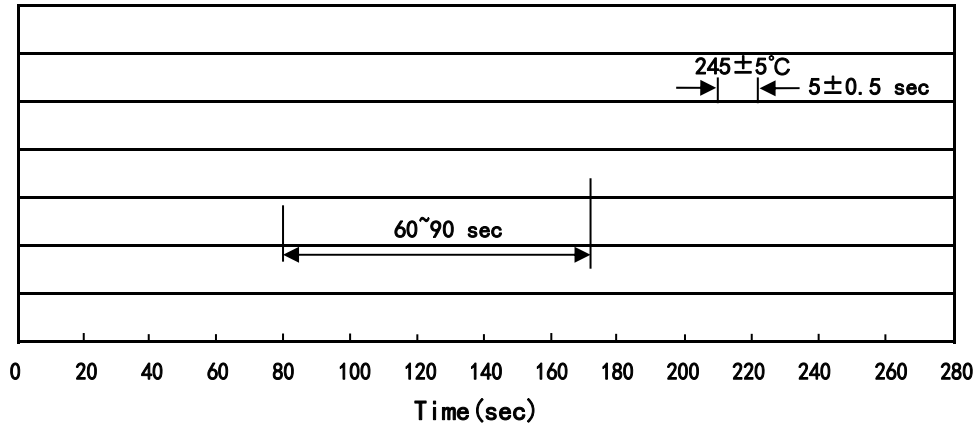
**/ Package Dimensions**



**LV10T100E**  
Rev.1 Jan.-2024



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Note:

- 1            150 180            60 90sec;            1.Preheating:150~180 , Time:60~90sec.
- 2            245 5            5 0.5sec;            2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3                       2 10 /sec.            3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5            10 1 sec.            Temp.:260±5            Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm <sup>3</sup> )		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366

/ Notices